

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the above-identified application.

**LISTING OF CLAIMS:**

1.-9. (Cancelled).

10. (Previously presented) A resin composition for printed wiring board which comprises a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound, and which further comprises a polyphenylene ether resin, wherein the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

11.-16. (Cancelled).

17. (Previously presented) A resin composition for printed wiring board which comprises a phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, a monovalent phenol compound, then mixing an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and which further comprises a poly-phenylene ether resin.

18.-30. (Cancelled).

31. (Previously presented) A resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound, and wherein the composition further comprises a polyphenylene ether resin.

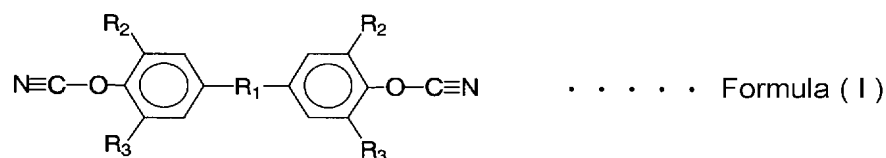
32.-43. (Cancelled).

44. (Original) A resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, a monovalent phenol compound and an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule in the presence of a polyphenylene ether resin.

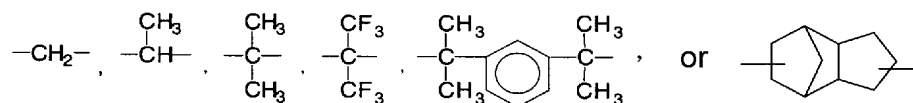
45.-49. (Cancelled).

50. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein the monovalent phenol compound is contained in an amount of 2 to 60 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

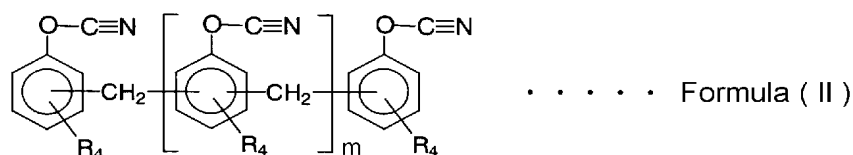
51. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



wherein  $R_1$  represents



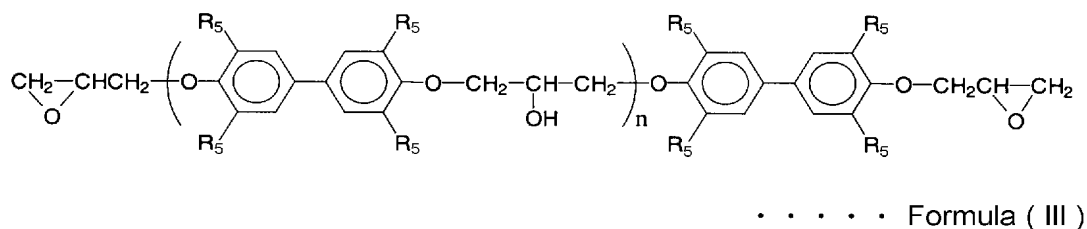
$R_2$  and  $R_3$  each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each is the same or different from each other,  
and a cyanate ester compound represented by the formula (II):



wherein  $R_4$  represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms,  $m$  represents an integer of 1 to 7,  
and a prepolymer thereof.

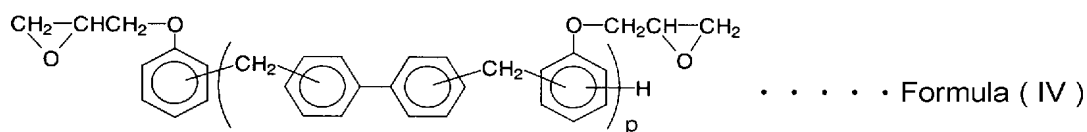
52. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl

structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



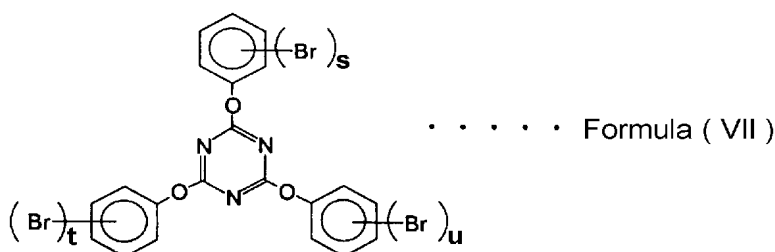
wherein R<sub>5</sub> each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

and an epoxy resin represented by the formula (IV):



wherein p represents an integer of 1 to 5.

53. (Previously presented) The resin composition for printed wiring board according to Claim 10 , wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane , bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



wherein s, t and u each represent an integer of 1 to 5, and each is the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

54. (Previously presented) The resin composition for printed wiring board according to Claim 10, which further comprises an antioxidant.

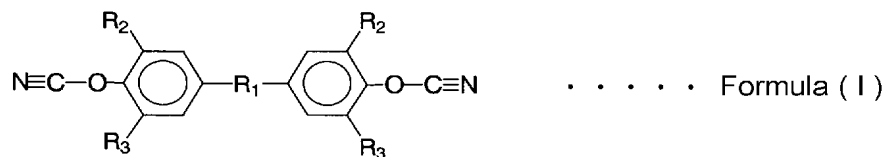
55. (Previously presented) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 10 in a solvent.

56.-59. (Cancelled).

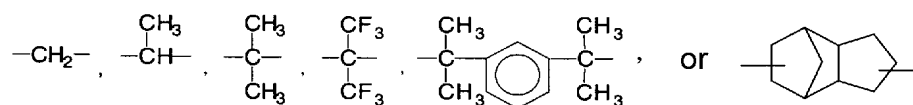
60. (Previously presented) The resin composition for printed wiring board according to Claim 17, wherein the phenol-modified cyanate ester oligomer is a phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and 2 to 60 parts by weight of the monovalent phenol compound, and the epoxy resin compound containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight.

61. (Previously presented) The resin composition for printed wiring board according to Claim 17, wherein the cyanate ester compound having 2 or more cyanate groups

in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):

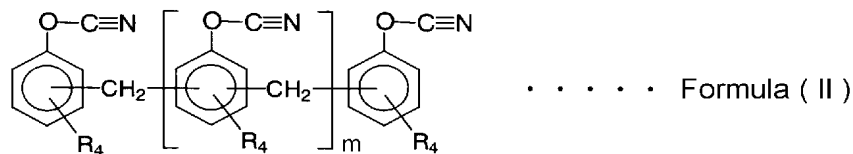


wherein R<sub>1</sub> represents



R<sub>2</sub> and R<sub>3</sub> each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each is the same or different from each other,

and a cyanate ester compound represented by the formula (II):

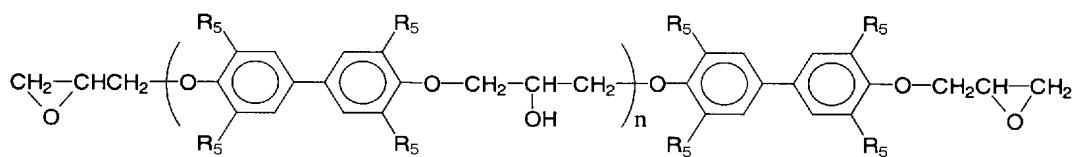


wherein R<sub>4</sub> represents a hydrogen atom or an alkyl group having 1 to 4 carbon

atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

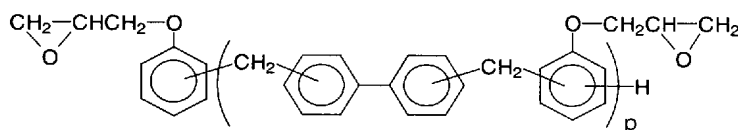
62. (Previously presented) The resin composition for printed wiring board according to Claim 17, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



• • • • • Formula ( III )

wherein R<sub>5</sub> each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

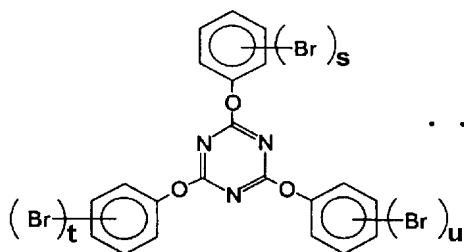
and an epoxy resin represented by the formula (IV):



• • • • • Formula ( IV )

wherein p represents an integer of 1 to 5.

63. (Previously presented) The resin composition for printed wiring board according to Claim 17, wherein the composition further comprises at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



• • • • • Formula ( VII )

wherein s, t and u each represent an integer of 1 to 5, and each is the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene, as a flame retardant.

64. (Previously presented) The resin composition for printed wiring board according to Claim 17, which further comprises an antioxidant.

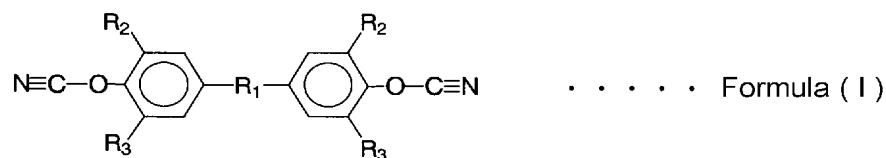
65. (Previously presented) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 17 in a solvent.

66.- 69. (Cancelled).

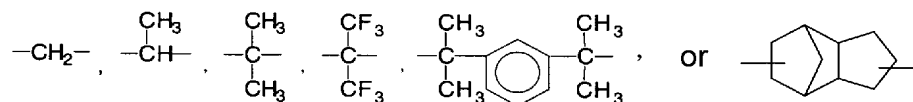
70. (Previously presented) The resin composition for printed wiring board according to Claim 31, wherein the epoxy/phenol-modified cyanate ester oligomer is an epoxy/phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, 10 to 250 parts by weight of the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and 2 to 60 parts by weight of the monovalent phenol compound.

71. (Previously presented) The resin composition for printed wiring board according to Claim 31, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



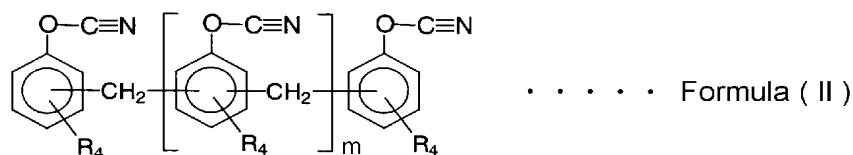


wherein  $R_1$  represents



$R_2$  and  $R_3$  each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each is the same or different from each other,

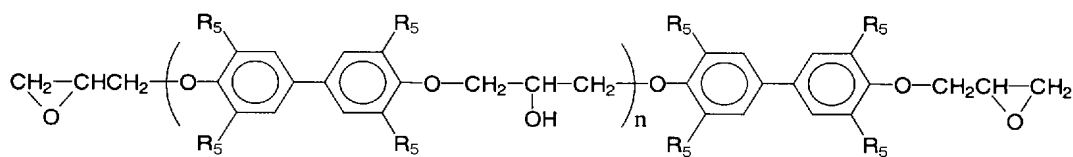
and a cyanate ester compound represented by the formula (II):



wherein  $R_4$  represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms,  $m$  represents an integer of 1 to 7,

and a prepolymer thereof.

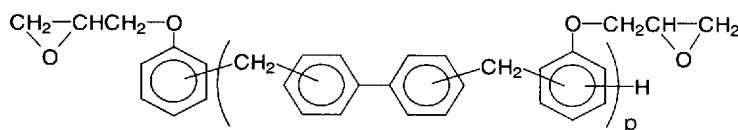
72. (Previously presented) The resin composition for printed wiring board according to Claim 31, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



. . . . . Formula ( III )

wherein R<sub>5</sub> each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

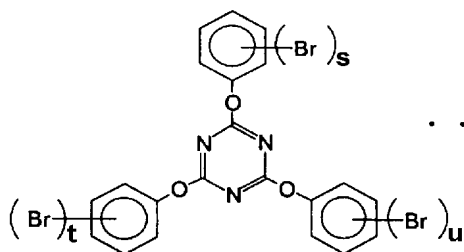
and an epoxy resin represented by the formula (IV):



. . . . . Formula ( IV )

wherein p represents an integer of 1 to 5.

73. (Previously presented) The resin composition for printed wiring board according to Claim 31, wherein the composition further comprises at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



. . . . . Formula ( VII )

wherein s, t and u each represent an integer of 1 to 5, and each is the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene, as a flame retardant.

74. (Previously presented) The resin composition for printed wiring board according to Claim 31, which further comprises an antioxidant.

75. (Previously presented) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 31 in a solvent.

76.-79. (Cancelled).

80. (Previously presented) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 44 in a solvent.

81.-86. (Cancelled).

87. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein said epoxy resin having a biphenyl structure in the molecule is a biphenyl epoxy resin.

88. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein said epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure is contained in an amount of 10 to 150 parts by weight

based on 100 parts by weight of the cyanate ester having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

89. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein said epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure is contained in an amount of 10 to 100 parts by weight based on 100 parts by weight of the cyanate ester having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

90. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein an amount of said at least one kind of an epoxy resin having a biphenyl structure is at least 50% by weight of a total weight of said epoxy resin in the resin composition.

91. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein an amount of said at least one kind of an epoxy resin having a biphenyl structure is at least 70% by weight of a total weight of said epoxy resin in the resin composition.

92. (Previously presented) The resin composition for printed wiring board according to Claim 10, wherein an amount of said at least one kind of an epoxy resin having a biphenyl structure is 100% by weight of a total weight of said epoxy resin in the resin composition.